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Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn) A method of manufacturing a three-dimensional mounted assembly comprising the steps of:

disposing a plurality of electronic parts on a mold and providing a plurality of interconnections on the mold;

filling a cavity formed by the mold with a molding material, and sealing the electronic parts and the interconnection with the molding material; and

curing the molding material, and removing the mold from the molding material.
2. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 1,

wherein the mold has a structure in which the three-dimensional body having the cavity is developed on a plane.
3. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 1,

wherein each of the interconnections includes a wire, and both ends of the wire are bonded to the mold.
4. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 3,

wherein a bonding pad is formed on the mold in advance, and the wire is bonded to the bonding pad.
5. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 1,

wherein the electronic parts and the interconnections are sealed with the molding material with a release agent applied to the mold.

6. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 1,

wherein the mold has a projection, and a recess, at least part of which is formed by an exposed portion of each of the interconnections, is formed in the molding material by providing part of each of the interconnections on an upper end surface of the projection.

7. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 5,

wherein the mold has a projection, and a recess, at least part of which is formed by an exposed portion of each of the interconnections, is formed in the molding material by providing part of each of the interconnections on an upper end surface of the projection.

8. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 6, further comprising a step of filling the recess with a conductive material.

9. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 7, further comprising a step of filling the recess with a conductive material.

10. (Withdrawn) The method of manufacturing a three-dimensional mounted assembly as defined in claim 1,

wherein at least one of the electronic parts is an optical device, and

wherein the optical device is mounted with an optical section thereof facing the mold, and the optical device is sealed with the molding material so as to avoid contact with the optical section.

11. (Currently Amended) A three-dimensional mounted assembly comprising:
a molded body;
a plurality of electronic parts sealed with the molded body; and
~~a plurality of an interconnections~~ interconnection ~~electrically connected to the~~
~~electronic parts and~~ sealed with the molded body,
wherein ~~one or more interconnections have a~~ the interconnection has its first exposed ~~surface~~ end facing outside the molded body, the first exposed ~~surface~~ end and a first side of the molded body being on the same first plane ~~and~~, the first exposed ~~surface~~ end not extending beyond the first plane, and
wherein ~~one or more the interconnections have a~~ interconnection has its second exposed ~~surface~~ end facing outside the molded body, the second exposed ~~surface~~ end and a second side of the molded body differing from the first side being on the same second plane and the second exposed ~~surface~~ end not extending beyond the second plane.

12-16. (Canceled)

17. (Original) The three-dimensional mounted assembly as defined in claim 11,
wherein each of the electronic parts is an optical device, and a hole linking an optical section of the optical device is formed in the molded body.

18. (Original) The three-dimensional mounted assembly as defined in claim 17,
wherein an optical fiber is inserted into the hole to form an optical module.

19. (Original) An optical transmission device comprising:
a plurality of the three-dimensional mounting assemblies as defined in claim 17; and
an optical fiber connected to each of the three-dimensional mounting assemblies.

20. (Original) The optical transmission device as defined in claim 19, further comprising a plug electrically connected to each of the three-dimensional mounting assemblies.

21. (Currently Amended) A three-dimensional mounted assembly comprising:
a molded body, the molded body having a first side formed by a first mold, the molded body having a second side formed by a second mold;
a plurality of electronic parts sealed with the molded body; and
~~a plurality of interconnections~~an interconnection~~electrically connected to the electronic parts and~~ sealed with the molded body,

wherein ~~one or more interconnections have a~~the interconnection has its first exposed ~~surface end facing outside the molded body and~~ formed by the first mold on a first side of the molded body such that the first exposed ~~surface end~~ and the first side of the molded body are on the same first plane and the first exposed ~~surface end~~ does not extend beyond the first plane, and

wherein ~~one or more interconnections have a~~the interconnection has its second exposed ~~surface end facing outside the molded body and~~ formed by the second mold on a second side of the molded body differing from the first side such that the second exposed ~~surface end~~ and the second side of the molded body are on the same second plane and the second exposed surface does not extend beyond the second plane.